Amendment Of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing Of Claims:

1. (Currently Amended) Microminiature image pickup device comprising:

image pickup element, optical glass furnished on the front surface of said image pickup element, a stacked circuit board that is furnished on the rear surface of said image pickup element and that has a wiring pattern, wherein said image pickup element is mounted to said stacked circuit board so that said rear surface is mounted on an edge of said stacked circuit board along said diametral direction, whereby length of said image pickup device in said length direction is reduced, and a connection member that electrically connects said image pickup element and the wiring pattern of said stacked circuit board;

said stacked circuit board being formed with insulated circuit boards, in which are packaged electronic circuits that include wiring patterns, stacked in multiple layers in the diametral direction perpendicular to the length direction of the microminiature image pickup device and having a cavity formed as an indentation in the diametral direction thereof;

a first electronic component mounted in said cavity, and a second electronic component mounted on the surface of said stacked circuit board.

2. (Previously Presented) Microminiature image pickup device described in Claim 1 wherein said first electronic component is connected to a wiring pattern formed on the bottom surface of said cavity.

3. (Previously Presented) Microminiature image pickup device described in Claim 1 wherein said first electronic component is mounted in said cavity in a bare chip state.

4. (Previously Presented) Microminiature image pickup device described in Claim 1wherein said image pickup device is a CCD device.

5. (Previously Presented) Microminiature image pickup device described in Claim 1 wherein said connection member is TAB tape.

6. (Previously Presented) Microminiature image pickup device described in Claim 2 wherein said first electronic component is mounted in said cavity in a bare chip state.

7. (Previously Presented) Microminiature image pickup device described in Claim 2 wherein said image pickup device is a CCD device.

8. (Previously Presented) Microminiature image pickup device described in Claim 3 wherein said image pickup device is a CCD device.

9. (Previously Presented) Microminiature image pickup device described in Claim 2 wherein said connection member is TAB tape.

10. (Previously Presented) Microminiature image pickup device described in Claim 3 wherein said connection member is TAB tape.

11. (Previously Presented) Microminiature image pickup device described in Claim 4 wherein said connection member is TAB tape.

12. (New) Microminiature image pickup device described in Claim 1 wherein said device is an endoscope.

13. (New) Microminiature image pickup device described in Claim 12 wherein said device is an endoscope.

14. (New) Microminiature image pickup device described in Claim 1 wherein said stacked circuit board has a height in said diametral direction substantially equal to a size of said rear surface where said stacked circuit board meets said rear surface, said height reduced in size at other points along said length direction.

15. (New) Microminiature image pickup device described in Claim 2 wherein said stacked circuit board has a height in said diametral direction substantially equal to a size of said rear surface where said stacked circuit board meets said rear surface, said height reduced in size at other points along said length direction.

16. (New) Microminiature image pickup device described in Claim 12 wherein said stacked circuit board has a height in said diametral direction substantially equal to a size of said rear surface where said stacked circuit board meets said rear surface, said height reduced in size at other points along said length direction.

17. (New) Microminiature image pickup device described in Claim 13 wherein said stacked circuit board has a height in said diametral direction substantially equal to a size of said rear surface where said stacked circuit board meets said rear surface, said height reduced in size at other points along said length direction.